DGG, DGV, OR DL PACKAGE

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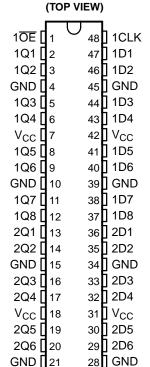
FEATURES

- Member of the Texas Instruments Widebus™
 Family
- Operates From 1.65 to 3.6 V
- Max t_{pd} of 4.2 ns at 3.3 V
- ±24-mA Output Drive at 3.3 V
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)

DESCRIPTION/ORDERING INFORMATION

This 16-bit edge-triggered D-type flip-flop is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74ALVCH16374 is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. It can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK) input, the Q outputs of the flip-flop take on the logic levels at the data (D) inputs. OE can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.



27 2D7

26 7 2D8

25 1 2CLK

2Q7 **1**22

2Q8 **∏**23

20E **1**24

OE does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments.

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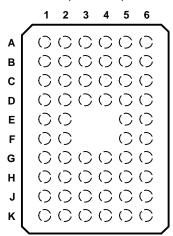


ORDERING INFORMATION

T _A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SSOP - DL	Tube	SN74ALVCH16374DL	ALVCH16374	
	330P - DL	Tape and reel	SN74ALVCH16374DLR	ALVCH16374	
-40°C to 85°C	TSSOP - DGG	Tape and reel	SN74ALVCH16374DGGR	ALVCH16374	
-40 C to 65 C	TVSOP - DGV	Tape and reel	SN74ALVCH16374DGVR		
	VFBGA - GQL	Tone and real	SN74ALVCH16374KR	VH374	
	VFBGA - ZQL (Pb-free)	Tape and reel	74ALVCH16374ZQLR		

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guideline are available at www.ti.com/sc/package.

GQL OR ZQL PACKAGE (TOP VIEW)



TERMINAL ASSIGNMENTS(1)

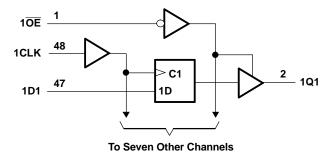
	1	2	3	4	5	6
Α	1 <u>OE</u>	NC	NC	NC	NC	1CLK
В	1Q2	1Q1	GND	GND	1D1	1D2
С	1Q4	1Q3	V _{CC}	V _{CC}	1D3	1D4
D	1Q6	1Q5	GND	GND	1D5	1D6
E	1Q8	1Q7			1D7	1D8
F	2Q1	2Q2			2D2	2D1
G	2Q3	2Q4	GND	GND	2D4	2D3
Н	2Q5	2Q6	V _{CC}	V _{CC}	2D6	2D5
J	2Q7	2Q8	GND	GND	2D8	2D7
K	2 0E	NC	NC	NC	NC	2CLK

(1) NC - No internal connection

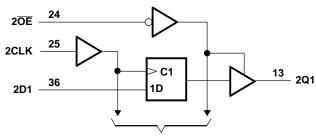
FUNCTION TABLE (each flip-flop)

	OUTPUT		
ŌĒ	CLK	D	Q
L	1	Н	Н
L	\uparrow	L	L
L	H or L	X	Q_0
Н	Χ	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)



Pin numbers shown are for the DGG, DGV, and DL packages.



To Seven Other Channels



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ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT	
V _{CC}	Supply voltage range	Supply voltage range				
VI	Input voltage range ⁽²⁾		-0.5	4.6	V	
Vo	Output voltage range ⁽²⁾⁽³⁾		-0.5	V _{CC} + 0.5	V	
I _{IK}	Input clamp current	V ₁ < 0		-50	mA	
I _{OK}	Output clamp current	V _O < 0		-50	mA	
Io	Continuous output current		±50	mA		
	Continuous current through each V _{CC} or GND			±100	mA	
		DGG package		70		
	Declare the analism of (4)	DGV package		58	°C/W	
θ_{JA}	Package thermal impedance ⁽⁴⁾	DL package		63		
		GQL/ZQL package		42		
T _{stg}	Storage temperature range		-65	150	°C	

⁽¹⁾ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS(1)

			MIN	MAX	UNIT	
V _{CC}	Supply voltage		1.65	3.6	V	
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}			
V_{IH}	High-level input voltage	V _{CC} = 2.3 V to 2.7 V	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		$0.35 \times V_{CC}$		
V_{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V	
		V _{CC} = 2.7 V to 3.6 V		0.8		
V _I	Input voltage	·	0	V _{CC}	V	
Vo	Output voltage		0	V _{CC}	V	
	IP of the of a street assessed	V _{CC} = 1.65 V		-4		
		V _{CC} = 2.3 V		-12	mA	
I _{OH}	High-level output current	V _{CC} = 2.7 V		-12		
		V _{CC} = 3 V		-24		
		V _{CC} = 1.65 V		4		
	Laur laural autout aumant	V _{CC} = 2.3 V		12	- mA	
I _{OL}	Low-level output current	V _{CC} = 2.7 V		12		
		V _{CC} = 3 V		24		
Δt/Δν	Input transition rise or fall rate	•		10	ns/V	
T _A	Operating free-air temperature		-40	85	°C	

⁽¹⁾ All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

⁽²⁾ The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ This value is limited to 4.6 V, maximum.

⁽⁴⁾ The package thermal impedance is calculated in accordance with JESD 51-7.

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ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

P	ARAMETER	TEST CONDITIONS	v _{cc}	MIN TYP(1	MAX	UNIT
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2		
		I _{OH} = -4 mA	1.65 V	1.2		
		$I_{OH} = -6 \text{ mA}$	2.3 V	2		
V _{OH}			2.3 V	1.7		V
		I _{OH} = -12 mA	2.7 V	2.2		
			3 V	2.4		
		$I_{OH} = -24 \text{ mA}$	3 V	2		
		$I_{OL} = 100 \mu\text{A}$	1.65 V to 3.6 V		0.2	
		I _{OL} = 4 mA	1.65 V		0.45	
		I _{OL} = 6 mA	2.3 V		0.4	V
V _{OL}		12 mA	2.3 V		0.7	\ \ \ \
		I _{OL} = 12 mA	2.7 V		0.4	
		I _{OL} = 24 mA	3 V		0.55	
I _I		$V_I = V_{CC}$ or GND	3.6 V		±5	μΑ
		V _I = 0.58 V	1.65 V	25	·	
		V _I = 1.07 V	1.65 V	-25		
		V _I = 0.7 V	2.3 V	45		
I _{I(hold)}		V _I = 1.7 V	2.3 V	-45		μΑ
		V _I = 0.8 V	3 V	75		
		V _I = 2 V	3 V	-75		
		V _I = 0 to 3.6 V ⁽²⁾	3.6 V		±500	
I _{OZ}		$V_O = V_{CC}$ or GND	3.6 V		±10	μΑ
I _{CC}		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		40	μΑ
ΔI_{CC}		One input at V _{CC} - 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V		750	μΑ
	Control inputs	V – V or CND	3.3 V	3	3	n.E
C _i	Data inputs	$V_I = V_{CC}$ or GND	3.3 V	6	3	pF
Co	Outputs	$V_O = V_{CC}$ or GND	3.3 V	7	,	pF

TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		V _{CC} =	1.8 V	V _{CC} = ± 0.2	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} = ± 0.	3.3 V 3 V	UNIT
		MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency		(1)		150		150		150	MHz
t _w	Pulse duration, CLK high or low	(1)		3.3		3.3		3.3		ns
t _{su}	Setup time, data before CLK↑	(1)		2.1		2.2		1.9		ns
t _h	Hold time, data after CLK↑	(1)		0.6		0.5		0.5		ns

⁽¹⁾ This information was not available at the time of publication.

All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.



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SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	PARAMETER FROM TO (INPUT) (OUTPUT		V _{CC} =	1.8 V	V _{CC} = : ± 0.2	2.5 V 2 V	V _{CC} =	2.7 V	V _{CC} = 3 ± 0.3	3.3 V 3 V	UNIT
	(INPUT)	(OUTPUT)	MIN	TYP	MIN	MAX	MIN	MAX	MIN	MAX	
f _{max}			(1)		150		150		150		MHz
t _{pd}	CLK	Q		(1)	1	5.3		4.9	1	4.2	ns
t _{en}	ŌĒ	Q		(1)	1	6.2		5.9	1	4.8	ns
t _{dis}	ŌĒ	Q		(1)	1	5.3		4.7	1.2	4.3	ns

⁽¹⁾ This information was not available at the time of publication.

OPERATING CHARACTERISTICS

 $T_A = 25^{\circ}C$

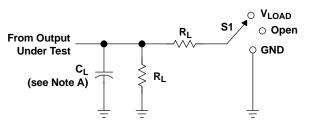
PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT	
	Outputs el		C - 50 % f - 10 MHz	(1)	31	30	pF
Cpd	Power dissipation capacitance	Outputs disabled C _L = 50 pF, f = 10 MHz		(1)	16	18	ρг

⁽¹⁾ This information was not available at the time of publication.

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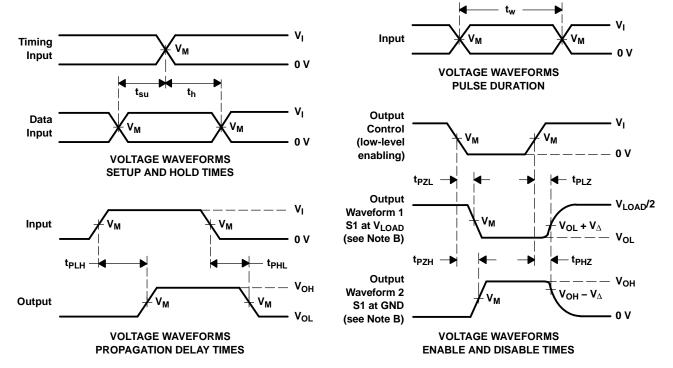
PARAMETER MEASUREMENT INFORMATION



TEST	S 1
t _{pd}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

LOAD CIRCUIT

	INPUT		J ,,	,,	_		v
V _{CC}	VI	t _r /t _f	V _M	V _{LOAD}	CL	R _L	$oldsymbol{V}_\Delta$
1.8 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	V _{CC}	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



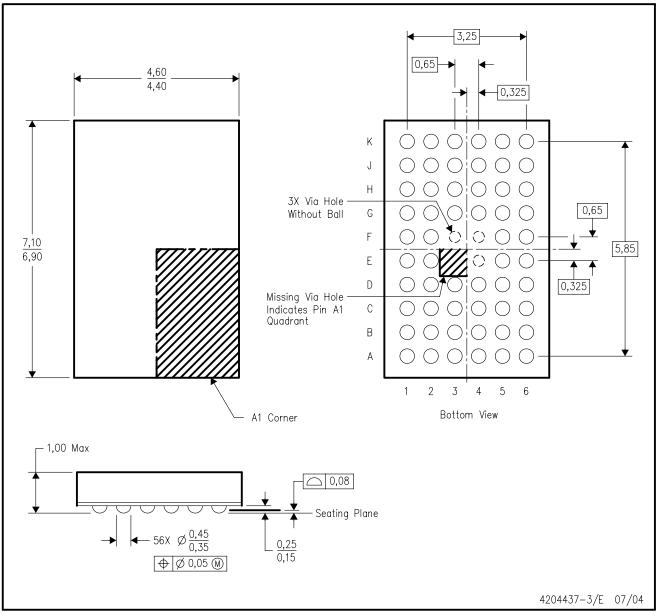
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{Ω} = 50 Ω .
- D. The outputs are measured one at a time, with one transition per measurement.
- E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. t_{PLH} and t_{PHL} are the same as t_{pd} .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

ZQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is lead-free. Refer to the 56 GQL package (drawing 4200583) for tin-lead (SnPb).



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

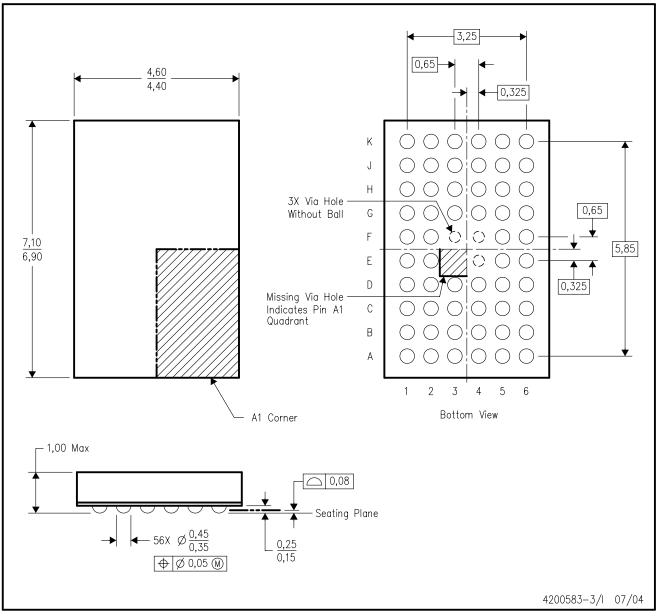
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



GQL (R-PBGA-N56)

PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



DL (R-PDSO-G**)

48 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

DGG (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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